

SOT650-1

plastic thermal enhanced very thin small outline package; no leads; 10 terminals; body 3 mm x 3

22 February 2024

Package information



1 Package summary

| | |
|---------------------------------------|--|
| Terminal position code | D (double) |
| Package type descriptive code | HVSON10 |
| Package type industry code | HVSON10 |
| Package style descriptive code | HVSON (thermal enhanced very thin small outline; no leads) |
| Package body material type | P (plastic) |
| JEDEC package outline code | MO-229 |
| Mounting method type | S (surface mount) |
| Issue date | 07-02-2024 |
| Manufacturer package code | SOT650 |

Table 1. Package summary

| Parameter | Min | Nom | Max | Unit |
|--------------------------------|-----|------|-----|------|
| package length | 2.9 | 3 | 3.1 | mm |
| package width | 2.9 | 3 | 3.1 | mm |
| seated height | - | 0.85 | 1 | mm |
| package height | - | 0.85 | - | mm |
| nominal pitch | - | 0.5 | - | mm |
| actual quantity of termination | - | 10 | - | |



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2 Package outline

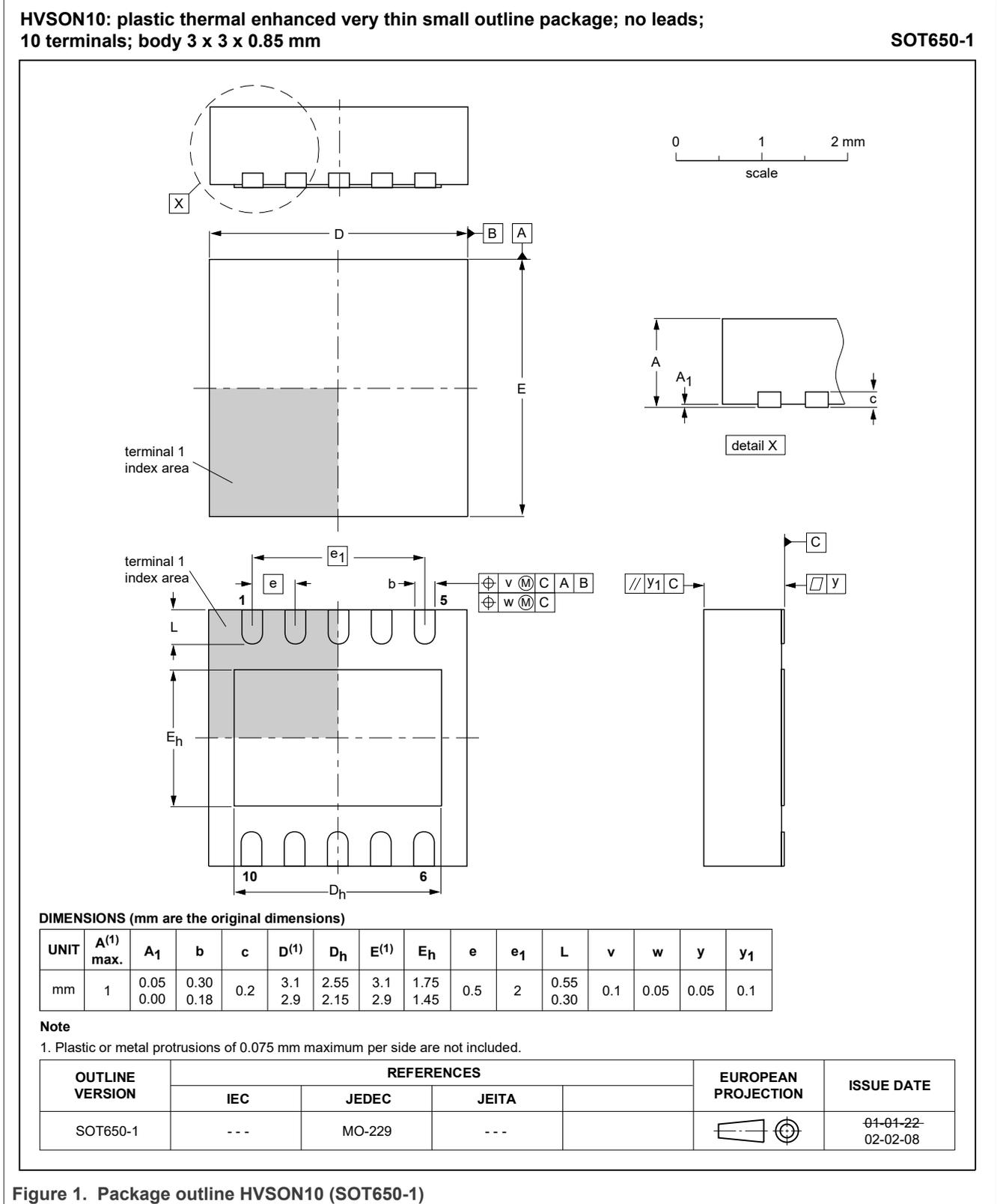
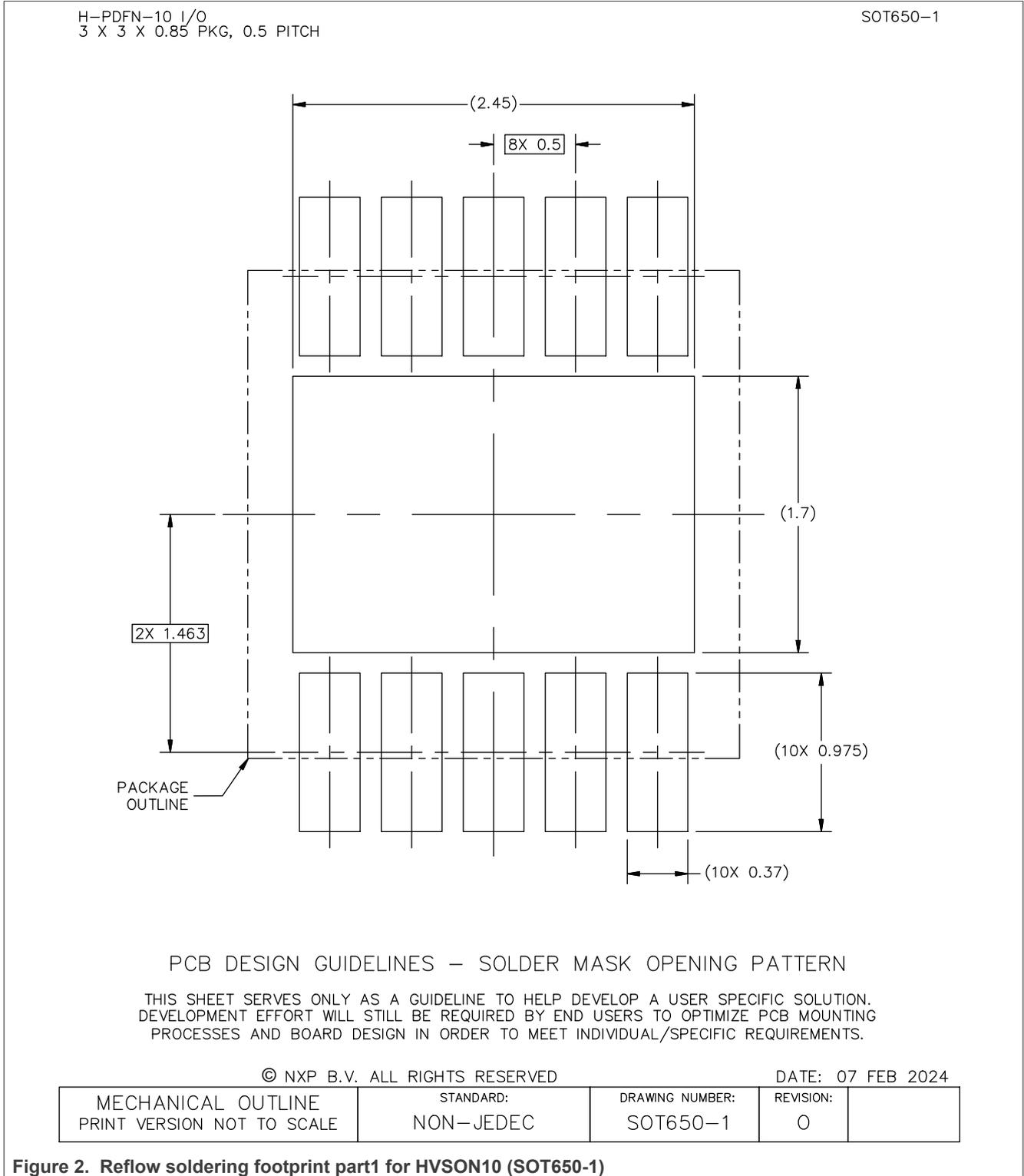


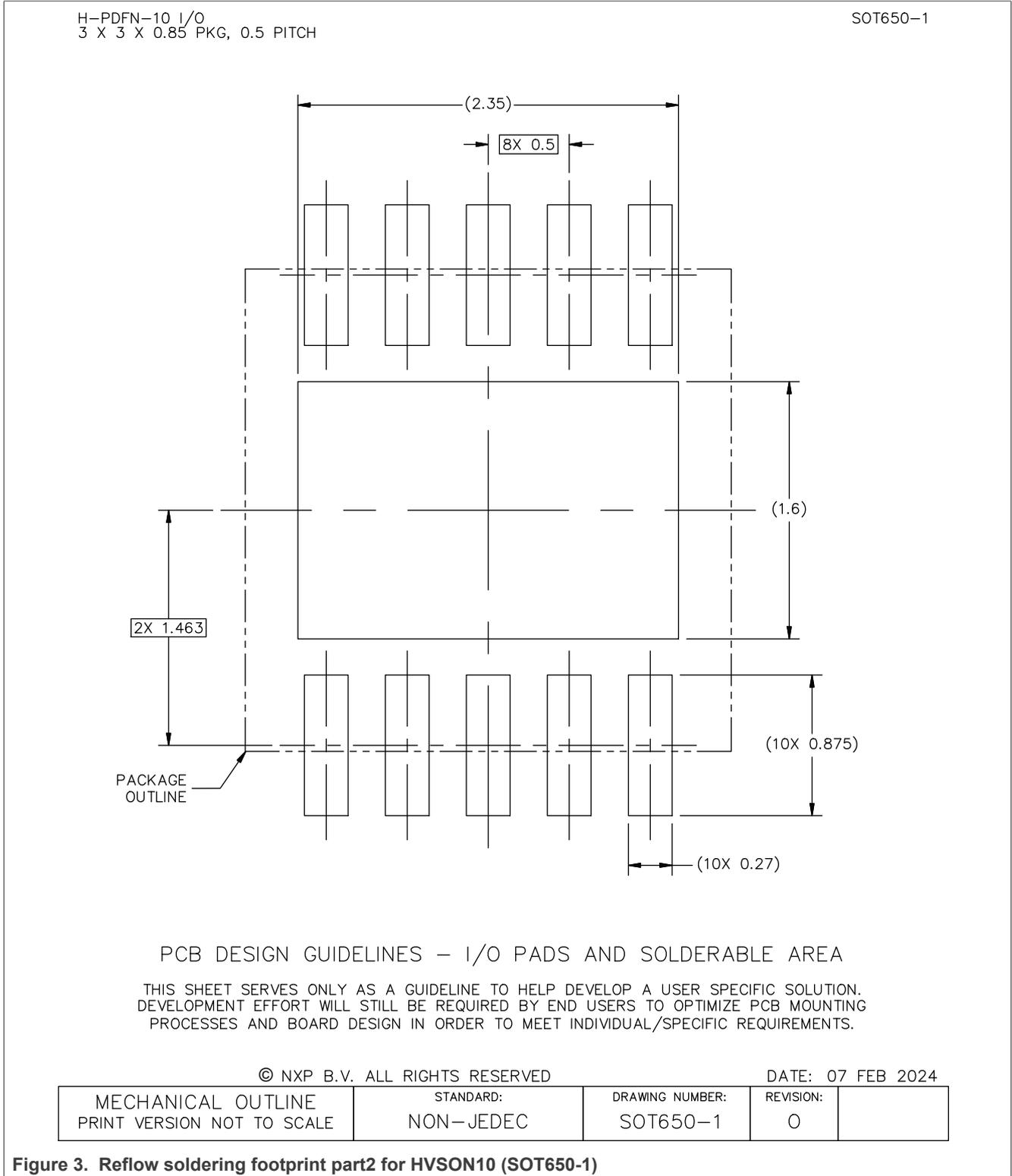
Figure 1. Package outline HVSON10 (SOT650-1)

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3 Soldering



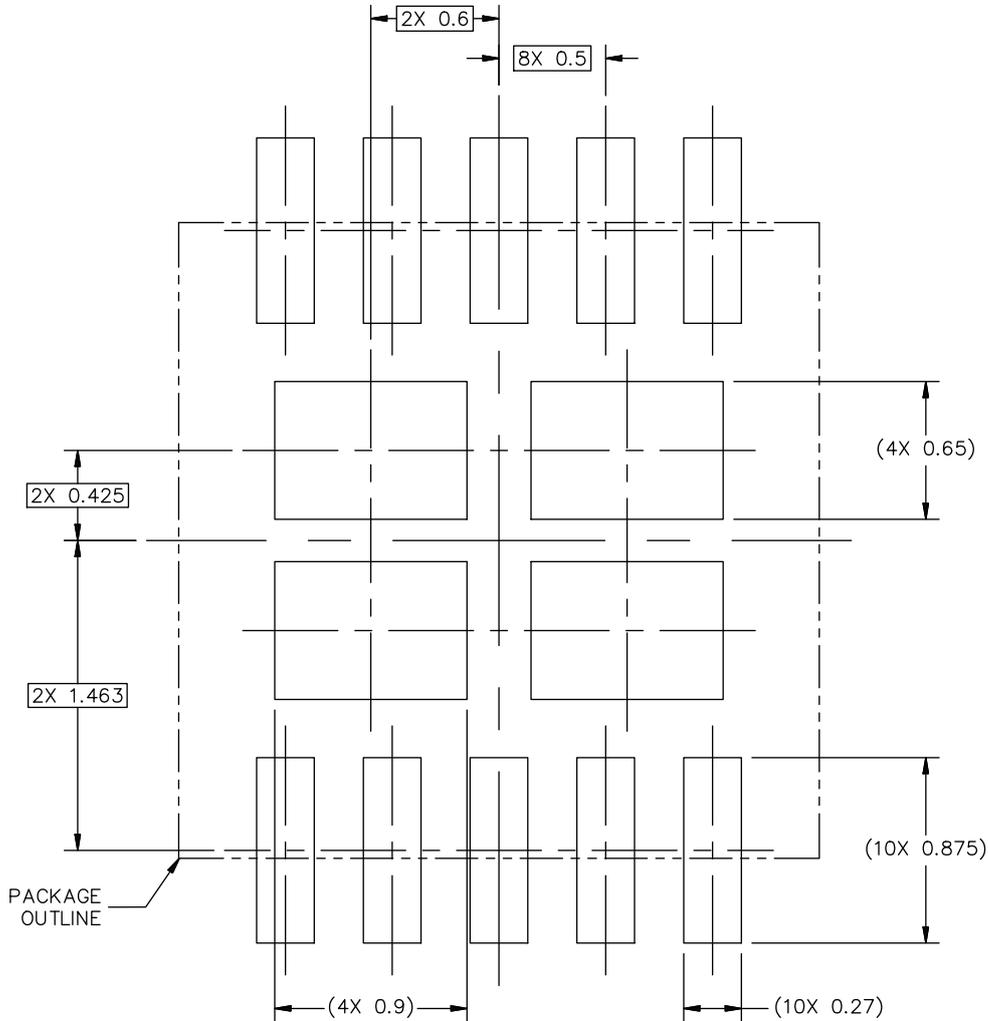
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H-PDFN-10 I/O
3 X 3 X 0.85 PKG, 0.5 PITCH

SOT650-1



RECOMMENDED STENCIL THICKNESS 0.125 OR 0.15

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION. DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL/SPECIFIC REQUIREMENTS.

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DATE: 07 FEB 2024

| | | | |
|--|------------------------|-----------------------------|----------------|
| MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE | STANDARD: NON-JEDEC | DRAWING NUMBER: SOT650-1 | REVISION: 0 |
|--|------------------------|-----------------------------|----------------|

Figure 4. Reflow soldering footprint part3 for HVSON10 (SOT650-1)

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4 Legal information

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